DATASHEET

Description

The 9DBL0242 / 9DBL0252 devices are 3.3V members of IDT's Full-Featured PCIe family. The devices support PCIe Gen1-4 Common Clocked (CC) and PCIe Gen2 Separate Reference Independent Spread (SRIS) systems. It offers a choice of integrated output terminations providing direct connection to 85Ω or 100Ω transmission lines. The 9DBL02P2 can be factory programmed with a user-defined power up default SMBus configuration.

Recommended Application

PCIe Gen1-4 clock distribution for Riser Cards, Storage, Networking, JBOD, Communications, Access Points

Output Features

- 2 1-200 MHz Low-Power (LP) HCSL DIF pairs
 - 9DBL0242 default ZOUT = 100Ω
 - 9DBL0252 default ZOUT = 85Ω
 - 9DBL02P2 factory programmable defaults
- Easy AC-coupling to other logic families, see IDT application note <u>AN-891</u>

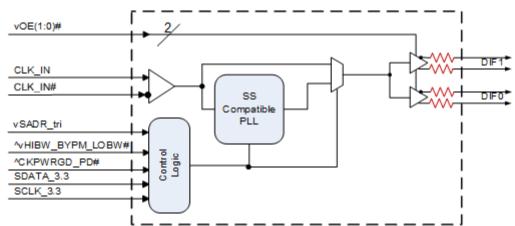
Key Specifications

- PCIe Gen1-2-3-4 CC compliant in ZDB mode
- PCIe Gen2 SRIS compliant in ZDB mode
- Supports PCIe Gen2-3 SRIS in fan-out mode
- DIF cycle-to-cycle jitter <50ps
- DIF output-to-output skew < 50ps
- Bypass mode *additive* phase jitter is 0 ps typical rms for PCIe
- Bypass mode *additive* phase jitter 160fs rms typ. @ 156.25M (1.5M to 10M)

Features/Benefits

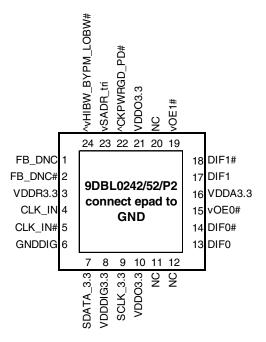
- Direct connection to 100Ω (xx42) or 85Ω (xx52) transmission lines; saves 8 resistors compared to standard PCIe devices
- 100mW typical power consumption in PLL mode; minimal power consumption
- SMBus-selectable features allows optimization to customer requirements:
 - control input polarity
 - control input pull up/downs
 - slew rate for each output
 - differential output amplitude
 - output impedance for each output
 - 50, 100, 125MHz operating frequency
- Customer defined SMBus power up default can be programmed into P1 device; allows exact optimization to customer requirements
- OE# pins; support DIF power management
- HCSL-compatible differential input; can be driven by common clock sources
- · Spread Spectrum tolerant; allows reduction of EMI
- Pin/SMBus selectable PLL bandwidth and PLL Bypass; minimize phase jitter for each application
- Outputs blocked until PLL is locked; clean system start-up
- Device contains default configuration; SMBus interface not required for device operation
- Three selectable SMBus addresses; multiple devices can easily share an SMBus segment
- Space saving 24-pin 4x4mm VFQFPN; minimal board space

Block Diagram



Note: Resistors default to internal on xx42/xx52 devices. P2 devices have programmable default impedances on an output-by-output basis.

Pin Configuration



24-pin VFQFPN, 4x4 mm, 0.5mm pitch

 ^ prefix indicates internal 120KOhm pull up resistor
 ^v prefix indicates internal 120KOhm pull up AND pull down resistor (biased to VDD/2)
 v prefix indicates internal 120KOhm pull down resistor

SMBus Address Selection Table

	SADR	Address	+ Read/Write bit
State of SADR on first application of	0	1101011	Х
CKPWRGD PD#	М	1101100	Х
	1	1101101	x

Note: If not using CKPWRGD (CKPWRGD tied to VDD3.3), all 3.3V VDD need to transition from 2.1V to 3.135V in <300usec.

Power Management Table

CKPWRGD PD#	CLK IN	SMBus	OEx# Pin	DIFx/D	IFx#	PLL
		OE bit		True O/P	Comp. O/P	T LL
0	Х	Х	Х	Low ¹	Low ¹	Off
1	Running	1	0	Running	Running	On ³
1	Running	1	1	Disabled ¹	Disabled ¹	On ³
1	Running	0	Х	Disabled ¹	Disabled ¹	On ³

1. The output state is set by B11[1:0] (Low/Low default)

2. Input polarities defined as default values for xx41/xx51 devices.

3. If Bypass mode is selected, the PLL will be off, and outputs will be running.

Power Connections

Pin Numb	Pin Number				
VDD	GND	Description			
3	25	Input receiver analog			
8	6	Digital Power			
10,21	25	DIF outputs			
16	25	PLL Analog			

PLL Operating Mode

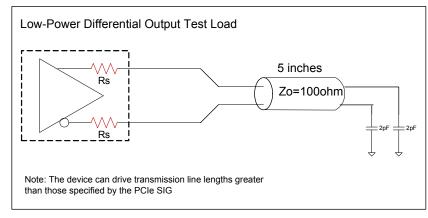
		Byte1 [7:6]	Byte1 [4:3]
HiBW_BypM_LoBW#	MODE	Readback	Control
0	PLL Lo BW	00	00
М	Bypass	01	01
1	PLL Hi BW	11	11

Pin Descriptions

Pin#	Pin Name	Pin Type	Description
			True clock of differential feedback. The feedback output and
1	FB_DNC	DNC	feedback input are connected internally on this pin. Do not connect
			anything to this pin.
			Complement clock of differential feedback. The feedback output
2	FB_DNC#	DNC	and feedback input are connected internally on this pin. Do not
			connect anything to this pin.
3	VDDR3.3	PWR	3.3V power for differential input clock (receiver). This VDD should
5	V DINO.0		be treated as an Analog power rail and filtered appropriately.
4	CLK_IN	IN	True Input for differential reference clock.
5	CLK_IN#	IN	Complementary Input for differential reference clock.
6	GNDDIG	GND	Ground pin for digital circuitry
7	SDATA_3.3	I/O	Data pin for SMBus circuitry, 3.3V tolerant.
8	VDDDIG3.3	PWR	3.3V digital power (dirty power)
9	SCLK_3.3	IN	Clock pin of SMBus circuitry, 3.3V tolerant.
10	VDDO3.3	PWR	Power supply for outputs, nominal 3.3V.
11	NC	N/A	No Connection.
12	NC	N/A	No Connection.
13	DIF0	OUT	Differential true clock output
14	DIF0#	OUT	Differential Complementary clock output
			Active low input for enabling DIF pair 0. This pin has an internal pull-
15	vOE0#	IN	down.
			1 =disable outputs, 0 = enable outputs
16	VDDA3.3	PWR	3.3V power for the PLL core.
17	DIF1	OUT	Differential true clock output
18	DIF1#	OUT	Differential Complementary clock output
			Active low input for enabling DIF pair 1. This pin has an internal pull-
19	vOE1#	IN	down.
			1 =disable outputs, 0 = enable outputs
20	NC	N/A	No Connection.
21	VDDO3.3	PWR	Power supply for outputs, nominal 3.3V.
			Input notifies device to sample latched inputs and start up on first
22	^CKPWRGD_PD#	IN	high assertion. Low enters Power Down Mode, subsequent high
			assertions exit Power Down Mode. This pin has internal pull-up
L			resistor.
23	vSADR_tri	LATCHED	
	_	IN	Selection Table.
		LATCHED	Trilevel input to select High BW, Bypass or Low BW mode. This
24	^vHIBW_BYPM_LOBW#	IN	pin is biased to VDD/2 (Bypass mode) with internal pull up/pull down
			resistors. See PLL Operating Mode Table for Details.
25	epad	GND	connect epad to ground.

NOTE: DNC indicates Do Not Connect anything to this pin.

Test Loads



remmations		
Device	Ζο (Ω)	Rs (Ω)
9DBL0242	100	None needed
9DBL0252	100	7.5
9DBL02P2	100	Prog.
9DBL0242	85	N/A
9DBL0252	85	None needed
9DBL02P2	85	Prog.

Alternate Terminations

The 9DBL family can easily drive LVPECL, LVDS, and CML logic. See <u>"AN-891 Driving LVPECL, LVDS, and CML Logic with IDT's "Universal" Low-Power HCSL Outputs</u>" for details.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBL0242 / 9DBL0252. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx				4.6	V	1,2
Input Voltage	V _{IN}		-0.5		V _{DD} +0.5	V	1,3
Input High Voltage, SMBus	VIHSMB	SMBus clock and data pins			3.9	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2500			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

² Operation under these conditions is neither implied nor guaranteed.

³ Not to exceed 4.6V.

Electrical Characteristics–Clock Input Parameters

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Crossover Voltage - DIF_IN	V _{CROSS}	Cross Over Voltage	150		900	mV	1
Input Swing - DIF_IN	V _{SWING}	Differential value	300			mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}$, $V_{IN} = GND$	-5		5	uA	
Input Duty Cycle	d _{tin}	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	J _{DIFIn}	Differential Measurement	0		125	ps	1

¹ Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through +/-75mV window centered around differential zero

Electrical Characteristics-SMBus Parameters

TA = T_{AMB;} Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	МАХ	UNITS	NOTES
SMBus Input Low Voltage	VILSMB	$V_{DDSMB} = 3.3V$			0.8	V	
SMBus Input High Voltage	VIHSMB	$V_{DDSMB} = 3.3V$	2.1		3.6	V	
SMBus Output Low Voltage	V _{OLSMB}	@ I _{PULLUP}			0.4	V	
SMBus Sink Current	I _{PULLUP}	@ V _{OL}	4			mA	
Nominal Bus Voltage	V _{DDSMB}		2.7		3.6	V	
SCLK/SDATA Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{SMB}	SMBus operating frequency			500	kHz	2,3

¹ Guaranteed by design and characterization, not 100% tested in production.

^{2.} The device must be powered up for the SMBus to function.

^{3.} The differential input clock must be running for the SMBus to be active

Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

 $TA = T_{AMB}$, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

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PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	МАХ	UNITS	NOTE
Supply Voltage	VDDx	Supply voltage for core and analog	3.135	3.3	3.465	V	
Ambient Operating Temperature	T _{AMB}	Industrial range	-40	25	85	°C	
Input High Voltage	V _{IH}	Single-ended inputs, except SMBus	0.75 V _{DDx}		V _{DDx} + 0.3	V	
Input Low Voltage	VIL		-0.3		$0.25 V_{DDx}$	V	
Input High Voltage	V _{IHtri}		$0.75 V_{DDx}$		$V_{DD} + 0.3$	V	
Input Mid Voltage	V _{IMtri}	Single-ended tri-level inputs ('_tri' suffix)	$0.4 V_{DDx}$	$0.5 V_{DDx}$	$0.6 V_{DDx}$	V	
Input Low Voltage	V _{ILtri}		-0.3		$0.25 V_{DDx}$	V	
	I _{IN}	Single-ended inputs, $V_{IN} = GND$, $V_{IN} = VDD$	-5		5	uA	
Input Current	I _{INP}	Single-ended inputs $V_{IN} = 0 V$; Inputs with internal pull-up resistors $V_{IN} = VDD$; Inputs with internal pull-down resistors	-50		50	uA	
		Bypass mode	1		200	MHz	2
land Francisco	_	100MHz PLL mode	60	100.00	140	°C V V V V uA uA	2
Input Frequency	F _{IN}	50MHz PLL mode	30	50.00	65	MHz	2
		125MHz PLL mode	75	125.00	175	MHz	2
Pin Inductance	L _{pin}				7	nH	1
	C _{IN}	Logic Inputs, except DIF_IN	1.5		5	pF	1
Capacitance	C _{INDIF_IN}	DIF_IN differential clock inputs	1.5		2.7	pF	1
	C _{OUT}	Output pin capacitance			6	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1	ms	1,2
Input SS Modulation Frequency PCIe	f _{MODINPCIe}	Allowable Frequency for PCIe Applications (Triangular Modulation)	30		33	kHz	
Input SS Modulation Frequency non-PCIe	f _{MODIN}	Allowable Frequency for non-PCle Applications (Triangular Modulation)	0		66	kHz	
OE# Latency	t _{LATOE#}	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	clocks	1,3
Tdrive_PD#	t _{DRVPD}	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t _F	Fall time of single-ended control inputs			5	ns	2
Trise	t _R	Rise time of single-ended control inputs			5	ns	2

¹Guaranteed by design and characterization, not 100% tested in production.

²Control input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV

Electrical Characteristics–DIF Low-Power HCSL Outputs

TA = T_{AMB.} Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

		, , , , , , , , , , , , , , , , , , , ,					
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on, fast setting	2	2.8	4	V/ns	1,2,3
Slew late	dV/dt	Scope averaging on, slow setting	1.2	1.9	3.1	V/ns V/ns % mV mV mV	1,2,3
Slew rate matching	∆dV/dt	Slew rate matching		7	20	%	1,2,4
Voltage High	V _{HIGH}	Statistical measurement on single-ended signal using oscilloscope math function. (Scope	660	768	850	m\/	7
Voltage Low	V _{LOW}	averaging on)	-150	-11	150		7
Max Voltage	Vmax	Measurement on single ended signal using		811	1150	m\/	7
Min Voltage	Vmin	absolute value. (Scope averaging off)	-300	-49			7
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	357	550	mV	1,5
Crossing Voltage (var)	∆-Vcross	Scope averaging off		14	140	mV	1,6

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all Vcross measurements in any particular system. Note that this is a subset of Vcross_min/max (Vcross absolute) allowed. The intent is to limit Vcross induced modulation by setting Δ-Vcross to be smaller than Vcross absolute.

⁷ At default SMBus settings.

Electrical Characteristics–Current Consumption

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
	I _{DDA}	VDDA, PLL Mode @100MHz		7	10	mA	
Operating Supply Current	IDDDIG	VDDDIG, PLL Mode @100MHz		3.4	5	mA	
	I _{DDO+R}	VDDO+VDDR, PLL Mode, All outputs @100MHz		20	25	mA	
	IDDRPD	VDDA, CKPWRGD_PD# = 0		0.6	1.0	mA	1
Powerdown Current	IDDDIGPD	VDDDIG, CKPWRGD_PD# = 0		3.0	4.3	mA	1
	I _{DDAOPD}	VDDO+VDDR, CKPWRGD_PD# = 0		0.9	1.3	mA	1

¹ Input clock stopped.

Electrical Characteristics–Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

TA = T _{AMB} , Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions							
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode (100MHz)	2	3.3	4	MHz	1,5
FLL Bandwidth	BW	-3dB point in Low BW Mode (100MHz)	1	1.5	2	MHz	1,5
PLL Jitter Peaking	t _{JPEAK}	Peak Pass band Gain (100MHz)		0.8	2	dB	1
Duty Cycle	t _{DC}	Measured differentially, PLL Mode	45	50	55	%	1
Duty Cycle Distortion	t _{DCD}	Measured differentially, Bypass Mode	-1	0.0	1	%	1,3
Skew, Input to Output	t _{pdBYP}	Bypass Mode, $V_T = 50\%$	2500	3406	4500	ps	1
Skew, input to Output	t _{pdPLL}	PLL Mode $V_T = 50\%$	-100	8	100	ps	1,4
Skew, Output to Output	t _{sk3}	V _T = 50%		21	55	ps	1,4
Jitter, Cycle to cycle	+	PLL mode		15	50	ps	1,2
	t _{jcyc-cyc}	Additive Jitter in Bypass Mode		0.1	1	ps	1,2

¹ Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

⁴ All outputs at default slew rate

⁵ The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

Electrical Characteristics–Filtered Phase Jitter Parameters - PCIe Common Clocked (CC) Architectures

T_{AMB} = over the specified operating range. Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUSTRY LIMIT	UNITS	Notes
	t _{jphPCleG1-CC}	PCIe Gen 1		23	32	86	ps (p-p)	1,2,3,5
		PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz)		0.6	0.8	3	ps (rms)	1,2,5
Phase Jitter, PLL Mode	t _{jphPCleG2-CC}	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz)		1.7	2.1	3.1	ps (rms)	1,2,5
	t _{jphPCleG3-CC}	PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz)		0.4	0.48	1	ps (rms)	1,2,5
	t _{jphPCleG4-CC}	PCIe Gen 4 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz)		0.4	0.48	0.5	ps (rms)	1,2,5
	t _{jphPCleG1-CC}	PCIe Gen 1		0.0	0.01		ps (p-p)	1,2,5
	t _{jphPCleG2-CC}	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz)		0.0	0.01		ps (rms)	1,2,4,5
<i>Additive</i> Phase Jitter, Bypass mode		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz)		0.0	0.01	n/a	ps (rms)	1,2,4,5
	t _{jphPCleG3-CC}	PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz)		0.0	0.01		ps (rms)	1,2,4,5
	t _{jphPCleG4-CC}	PCIe Gen 4 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz)		0.0	0.01		ps (rms)	1,2,4,5

¹ Applies to all outputs.

² Based on PCIe Base Specification Rev4.0 version 0.7draft. See http://www.pcisig.com for latest specifications.

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS values additive jitter is calculated by solving the following equation for b $[a^{2}+b^{2}=c^{2}]$ where a is rms input jitter and c is rms total jitter.

⁵ Driven by 9FGL0841 or equivalent

Electrical Characteristics–Filtered Phase Jitter Parameters - PCIe Separate Reference Independent Spread (SRIS) Architectures⁵

T_{AMB} = over the specified operating range. Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUSTRY LIMIT	UNITS	Notes
Phase Jitter, PLL Mode	t _{jphPCIeG2} . SRIS	PCIe Gen 2 (PLL BW of 16MHz,CDR = 5MHz)		1.2	1.5	2	ps (rms)	1,2,5
	t _{jphPCleG3-} SRIS	PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz)	n/a		0.7	ps (rms)	1,2,5,6	
Additive Phase Jitter,	t _{jphPCIeG2} . SRIS	PCIe Gen 2 (PLL BW of 16MHz,CDR = 5MHz)		0.0	0.01	2/2	ps (rms)	1,2,4,5
Bypass mode	t _{jphPCleG3} . SRIS	PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz)		0.0	0.01	n/a	ps (rms)	1,2,4,5

¹Guaranteed by design and characterization, not 100% tested in production.

² Based on PCIe Base Specification Rev3.1a. These filters are different than Common Clock filters. See http://www.pcisig.com for latest specifications.

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS values, additive jitter is calculated by solving the following equation for b [a²+b²=c²] where a is rms input jitter and c is rms total jitter.

⁵ As of PCIe Base Specification Rev4.0 draft 0.7, SRIS is defined as "implementation dependent", with no firm specifications.

⁶ Certain customers have suggested a 0.7ps spec limit for Gen3 SRIS The device supports PCIe Gen3 SRIS in bypass mode.

Electrical Characteristics–Unfiltered Phase Jitter Parameters

 $TA = T_{AMB}$, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

						INDUSTRY		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	LIMIT	UNITS	Notes
Additive Phase Jitter,	t _{jph156M}	156.25MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz		159		N/A	fs (rms)	1,2,3
Fanout Mode	t _{jph156M12k} - 20	156.25MHz, 12kHz to 20MHz, -20dB/decade rollover <12kHz, -40db/decade rolloff > 20MHz		363		N/A	fs (rms)	1,2,3

¹Guaranteed by design and characterization, not 100% tested in production.

² DRiven by Rohde&Schartz SMA100

³ For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)² - (input jitter)²]

General SMBus Serial Interface Information

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

	Index Bl	ock V	Vrite Operation
Controll	er (Host)		IDT (Slave/Receiver)
Т	starT bit		
Slave A	Address		
WR	WRite		
			ACK
Beginning	g Byte = N		
			ACK
Data Byte	Count = X		
			ACK
Beginnin	ig Byte N		
			ACK
0		×	
0		X Byte	0
0		Ð	0
			0
Byte N	+ X - 1		
			ACK
Р	stoP bit		

Note: SMBus Address is Latched on SADR pin. Unless otherwise indicated, default values are for the xx42 and xx52. P2 devices are fully factory programmable.

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

	Index Block F	Read O	peration
Cor	ntroller (Host)		IDT (Slave/Receiver)
Т	starT bit		
SI	ave Address		
WR	WRite	_	
			ACK
Begi	nning Byte = N		
		-	ACK
RT	Repeat starT	-	
SI	ave Address		
RD	ReaD		
			ACK
		_	Data Byte Count=X
	ACK		
		_	Beginning Byte N
	ACK	_	
		ę	0
	0	X Byte	0
	0	×	0
	0		
			Byte N + X - 1
Ν	Not acknowledge		
Р	stoP bit		

SMBus Table: Output Enable Register ¹

Byte 0	Name	Control Function	Туре	0	1	Default			
Bit 7		Reserved	d l			0			
Bit 6		Reserved	ł			0			
Bit 5	Reserved								
Bit 4	DIF OE1	Output Enable	RW	See P11[1:0]	Soo P11[1:0]	Soo P11[1:0]	See B11[1:0]	Pin Control	1
Bit 3	DIF OE0	Output Enable	RW		Pin Control	1			
Bit 2		Reserved	3			0			
Bit 1	Reserved								
Bit 0	Reserved								

1. A low on these bits will overide the OE# pin and force the differential output to the state indicated by B11[1:0] (Low/Low default)

SMBus Table: PLL Operating Mode and Output Amplitude Control Register

Byte 1	Name	Control Function	Туре	0	1	Default
Bit 7	PLLMODERB1	PLL Mode Readback Bit 1	R	See PLL Operat	ing Mode Table	Latch
Bit 6	PLLMODERB0	PLL Mode Readback Bit 0	R	See FLL Operat		Latch
Bit 5	PLLMODE_SWCNTRL	Enable SW control of PLL Mode	RW	Values in B1[7:6] set PLL Mode	Values in B1[4:3] set PLL Mode	0
Bit 4	PLLMODE1	PLL Mode Control Bit 1	RW ¹	See PLL Operat	ing Mode Table	0
Bit 3	PLLMODE0	PLL Mode Control Bit 0	RW^1	See FLL Operat		0
Bit 2		Reserved				1
Bit 1	AMPLITUDE 1	Controls Output Amplitude	RW	00 = 0.60V 01= 0.68V		1
Bit 0	AMPLITUDE 0		RW	10 = 0.75V	11 = 0.85V	0

1. B1[5] must be set to a 1 for these bits to have any effect on the part.

SMBus Table: Slew Rate Control Register

Byte 2	Name	Control Function	Туре	0	1	Default
Bit 7		Reserved				1
Bit 6		Reserved				1
Bit 5	Reserved					
Bit 4	SLEWRATESEL DIF1	Slew rate selection	RW	Slow Setting	Fast Setting	1
Bit 3	SLEWRATESEL DIF0	Slew rate selection	RW	Slow Setting	Fast Setting	1
Bit 2		Reserved				1
Bit 1	Reserved					
Bit 0		Reserved				1

Note: See "Low-Power HCSL Outputs" table for slew rates.

SMBus Table: Slew Rate Control Register

Byte 3	Name	Control Function	Туре	0	1	Default
Bit 7		Reserved				1
Bit 6		Reserved				1
Bit 5	FREQ_SEL_EN	Enable SW selection of frequency	RW	SW frequency change disabled	SW frequency change enabled	0
Bit 4	FSEL1	Freq. Select Bit 1	RW ¹	00 = 100M,	10 = 125M	0
Bit 3	FSEL0	Freq. Select Bit 0	RW ¹	01 = 50M, 1 ⁻	1= Reserved	0
Bit 2		Reserved	•			1
Bit 1	Reserved					
Bit 0	SLEWRATESEL FB	Adjust Slew Rate of FB	RW	Slow Setting	Fast Setting	1
1 B3[5] m	ust he set to a 1 for these hits	to have any effect on the part				

1. B3[5] must be set to a 1 for these bits to have any effect on the part.

Byte 4 is Reserved

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SMBus Table: Revision and Vendor ID Register

Byte 5	Name	Control Function	Туре	0	1	Default
Bit 7	RID3		R		0	
Bit 6	RID2	Revision ID	R	B rev =	0	
Bit 5	RID1		R	Diev-	0	
Bit 4	RID0		R		1	
Bit 3	VID3		R			0
Bit 2	VID2	VENDOR ID	R	0001	0001 = IDT	
Bit 1	VID1	VENDOR ID	R	0001 – 101		0
Bit 0	VID0		R			1

SMBus Table: Device Type/Device ID

Byte 6	Name	Control Function	Туре	0	1	Default
Bit 7	Device Type1	Device Type	RW	00 = FGx, 01 = DBx ZDB/FOB,		0
Bit 6	Device Type0	Вемсе Туре	RW	10 = DMx, 1	1	
Bit 5	Device ID5		RW			0
Bit 4	Device ID4		RW		0	
Bit 3	Device ID3	Device ID	RW	000010binary or 02 hex		0
Bit 2	Device ID2		RW			0
Bit 1	Device ID1		RW			1
Bit 0	Device ID0]	RW			0

SMBus Table: Byte Count Register

Byte 7	Name	Control Function	Туре	0	1	Default	
Bit 7	Reserved						
Bit 6	Reserved						
Bit 5	Reserved						
Bit 4	BC4		RW			0	
Bit 3	BC3		RW	Writing to this regist	er will configure how	1	
Bit 2	BC2	Byte Count Programming	RW	many bytes will be r	ead back, default is	0	
Bit 1	BC1		RW	= 8 b	ytes.	0	
Bit 0	BC0		RW			0	

Bytes 8 and 9 are Reserved

SMBus Table: PD_Restore

Byte 10	Name	Control Function	Туре	0	1	Default	
Bit 7	Reserved						
Bit 6	Power-Down (PD) Restore	Power-Down (PD) Restore Restore Default Config. In PD RW Clear Config in PD Keep Config in PD					
Bit 5	Reserved						
Bit 4	Reserved						
Bit 3		Reserved				0	
Bit 2		Reserved				0	
Bit 1	Reserved					0	
Bit 0		Reserved				0	

SMBus Table: Stop State and Impedance Control

Byte 11	Name	Control Function	Туре	0	1	Default	
Bit 7	FB_imp[1]	FB Zout	RW	00=33Ω DIF Zout	10=100Ω DIF Zout	see Note	
Bit 6	FB_imp[0]	FB Zout RW 01=85Ω DIF Zout 11 = Res		11 = Reserved	See Note		
Bit 5	Reserved						
Bit 4		Reserved					
Bit 3		Reserved				0	
Bit 2		Reserved				0	
Bit 1	STP[1]	True/Complement DIF Output		00 = Low/Low	10 = High/Low	0	
Bit 0	STP[0]	01 = HiZ/HiZ	11 = Low/High	0			

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Impedance Control

Byte 12	Name	Control Function	Туре	0	1	Default
Bit 7	DIF0_imp[1]	DIF0 Zout	RW	00=33Ω DIF Zout	10=100Ω DIF Zout	see Note
Bit 6	DIF0_imp[0]		RW	01=85Ω DIF Zout	11 = Reserved	See Note
Bit 5	Reserved					
Bit 4	Reserved					
Bit 3		Reserved				Х
Bit 2		Reserved				Х
Bit 1	Reserved					Х
Bit 0	Reserved					

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Impedance Control

Byte 13	Name	Control Function	Туре	0	1	Default	
Bit 7	Reserved						
Bit 6	Reserved						
Bit 5	Reserved						
Bit 4	Reserved						
Bit 3		Reserved				Х	
Bit 2		Reserved				Х	
Bit 1	DIF1_imp[1]	DIF1 Zout	RW	00=33Ω DIF Zout	10=100Ω DIF Zout	see Note	
Bit 0	DIF1_imp[0]	DIF1 Zout	RW	01=85Ω DIF Zout	11 = Reserved	SEE NULE	

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Pull-up Pull-down Control

Byte 14	Name	Control Function	Туре	0	1	Default	
Bit 7	OE0_pu/pd[1]	OE0 Pull-up(PuP)/	RW	00=None	10=Pup	0	
Bit 6	OE0_pu/pd[0]	Pull-down(Pdwn) control	RW	01=Pdwn	11 = Pup+Pdwn	1	
Bit 5	Reserved						
Bit 4	Reserved						
Bit 3		Reserved				Х	
Bit 2		Reserved					
Bit 1	Reserved						
Bit 0		Reserved				Х	

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Pull-up Pull-down Control

Byte 15	Name	Control Function	Туре	0	1	Default		
Bit 7		Reserved				Х		
Bit 6		Reserved						
Bit 5	Reserved							
Bit 4	Reserved							
Bit 3		Reserved				Х		
Bit 2		Reserved				Х		
Bit 1	OE1_pu/pd[1]	OE1 Pull-up(PuP)/	RW	00=None	10=Pup	0		
Bit 0	OE1_pu/pd[0]	OE1_pu/pd[0] Pull-down(Pdwn) control RW 01=Pdwn				1		

Note: These values are for xx42, and xx52. P2 is factory programmable.

SMBus Table: Pull-up Pull-down Control

Byte 16	Name	Control Function	Туре	0	1	Default		
Bit 7	Reserved							
Bit 6		Reserved						
Bit 5	Reserved							
Bit 4	Reserved							
Bit 3		Reserved				Х		
Bit 2		Reserved				Х		
Bit 1	CKPWRGD_PD_pu/pd[1]	CKPWRGD_PD Pull-up(PuP)/	RW	00=None	10=Pup	1		
Bit 0	CKPWRGD_PD_pu/pd[0]	Pull-down(Pdwn) control	RW	01=Pdwn	11 = Pup+Pdwn	0		

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

Bytes 17 is Reserved

SMBus Table: Polarity Control

Byte 18	Name	Control Function	Туре	0	1	Default
Bit 7	Reserved					
Bit 6	Reserved					
Bit 5	Reserved					
Bit 4	OE1_polarity	Sets OE1 polarity	RW	Enabled when Low	Enabled when High	0
Bit 3	OE0_polarity	Sets OE0 polarity	RW	Enabled when Low	Enabled when High	0
Bit 2		Reserved				Х
Bit 1	Reserved					
Bit 0		Reserved				Х

SMBus Table: Polarity Control

Byte 19	Name	Control Function	Туре	0	1	Default	
Bit 7	Reserved						
Bit 6	Reserved						
Bit 5	Reserved						
Bit 4	Reserved						
Bit 3	Reserved						
Bit 2		Reserved				0	
Bit 1		Reserved				0	
Bit 0	CKPWRGD_PD	Determines CKPWRGD_PD polarity	RW	Power Down when Low	Power Down when High	0	

Marking Diagrams



Notes:

- 1. "LOT" is the lot sequence number.
- 2. "YYWW" is the last two digits of the year and week that the part was assembled.
- 3. Line 2: truncated part number
- 4. "I" denotes industrial temperature range device.

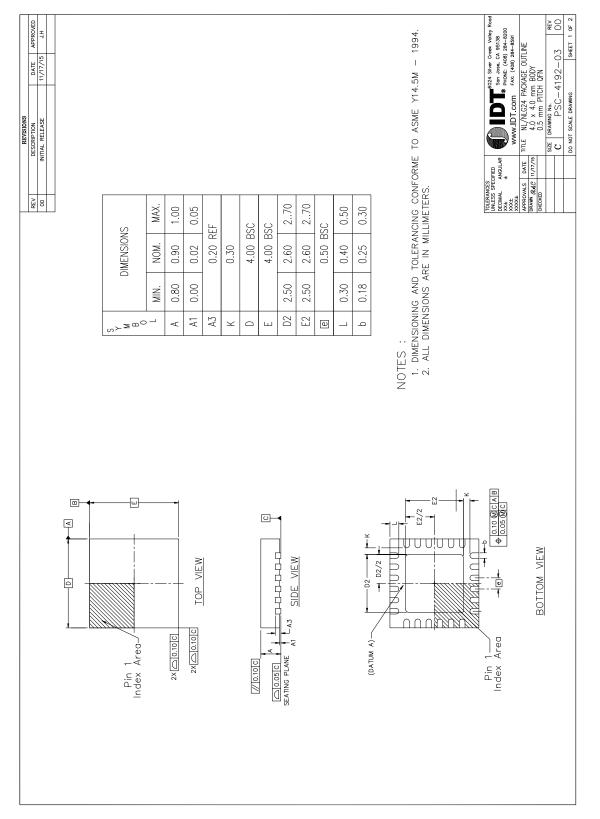
Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	PKG	TYP VALUE	UNITS	NOTES
	Θ _{JC}	Junction to Case		62	°C/W	1
	Θ _{Jb}	Junction to Base		5.4	°C/W	1
Thermal Resistance	Θ _{JA0}	Junction to Air, still air	NLG20	50	°C/W	1
memai nesistance	Θ _{JA1}	Junction to Air, 1 m/s air flow	NLG24	43	°C/W	1
	Θ _{JA3}	Junction to Air, 3 m/s air flow		39	°C/W	1
	Θ _{JA5}	Junction to Air, 5 m/s air flow		38	°C/W	1

¹ePad soldered to board

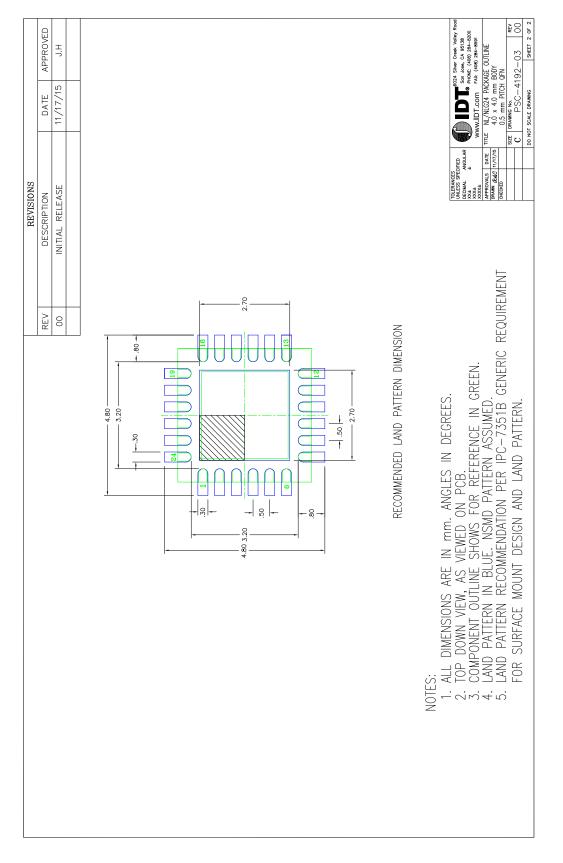
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Package Outline and Dimensions (NLG24)



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Package Outline and Dimensions, cont. (NLG24)



Ordering Information

Part / Order Number	Notes	Shipping Packaging	Package	Temperature
9DBL0242BKILF	100Ω	Tubes	24-pin VFQFPN	-40 to +85° C
9DBL0242BKILFT	10052	Tape and Reel	24-pin VFQFPN	-40 to +85° C
9DBL0252BKILF	85Ω	Tubes	24-pin VFQFPN	-40 to +85° C
9DBL0252BKILFT	0322	Tape and Reel	24-pin VFQFPN	-40 to +85° C
9DBL02P2BxxxKILF	Factory configurable.	Tubes	24-pin VFQFPN	-40 to +85° C
9DBL02P2BxxxKILFT	Contact IDT for addtional information.	Tape and Reel	24-pin VFQFPN	-40 to +85° C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"B" is the device revision designator (will not correlate with the datasheet revision).

"xxx" is a unique factory assigned number to identify a particular default configuration.

Revision History

Rev.	Initiator	Issue Date	Description	Page #
A	RDW	5/26/20106	 Updated all electrical tables with char data, changed additive phase jitter frequency from 125M to 156.25MHz and move to final. Updated front page text Updated default value of Byte 0 from 38 hex to 18 hex Updated default value of Byte 5 from 01 hex to 11 hex Indicated that Byte 6 is Read/Write Update DS title 	Various
В	RDW	5/27/2016	 Changed '1' value in Byte 0 to indicate "Pin Control" Stylistic update to block diagram Minor updates to SMBus registers 0 and 1 for Readability Corrected Byte 11 description for the '10' and '11' cases. Front page text update for family consistency. Updated ordering information. 	Various
С	RDW	5/31/2016	1. Minor corrections to Byte 1 [1:0] and Byte 11 [1:0]	
D	RDW	6/8/2016	 Electrical Table and SMBus Updates/Corrections Release to final. 	Various
E	RDW	10/6/2016	1. Slight updates to PCIe SRIS Spec table to reflect PCI SIG Updates	9
F	RDW	2/8/2017	Renamed datasheet to 9DBL0242/9DBL0252	Various



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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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